



Material Content Data Sheet



Sales Product Name		BTS7012-2EPA		Issued		9. January 2019		
MA#		MA002020034						
Package		PG-TSDSO-14-22		Weight*		65.19 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.263	1.94	1.94	19368	19368
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		145	
	non noble metal	zinc	7440-66-6	0.038	0.06		578	
	non noble metal	iron	7439-89-6	0.754	1.16		11566	
wire	non noble metal	copper	7440-50-8	30.617	46.96	48.19	469635	481924
	non noble metal	copper	7440-50-8	0.709	1.09	1.09	10878	10878
	encapsulation	organic material	carbon black	1333-86-4	0.087	0.13		1331
	plastics	epoxy resin	-	3.384	5.19		51905	
	inorganic material	silicondioxide	60676-86-0	25.451	39.04	44.36	390394	443630
leadfinish	non noble metal	tin	7440-31-5	1.642	2.52	2.52	25181	25181
plating	noble metal	silver	7440-22-4	0.816	1.25	1.25	12517	12517
glue	plastics	epoxy resin	-	0.074	0.11		1138	
	noble metal	silver	7440-22-4	0.350	0.54	0.65	5364	6502
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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